

Title (en)

ENCAPSULATION, MEMS AND ENCAPSULATION METHOD

Title (de)

VERKAPSELUNG, MEMS SOWIE VERFAHREN ZUM VERKAPSELN

Title (fr)

ENCAPSULAGE, SYSTÈME MICRO-ÉLECTROMÉCANIQUE ET PROCÉDÉ D'ENCAPSULAGE

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2010028884A2] The invention relates to the encapsulation (4) of a sensitive mechanical component structure (3) on a semiconductor substrate (2) by means of a film (5) that covers the component structure (3) and has at least one polymer layer (8). At least one cavity (7) is provided between the component structure (3) and the film (5). According to the invention, the film (5) is penetrated by at least one via (15).

IPC 8 full level

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Citation (search report)

See references of WO 2010028884A2

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DOCDB simple family (publication)

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